产品规格书
PRODUCT SPECIFICATION

客户名称 CUSTOMER	
宏业产品系列 PRODUCT SERIES	BCMS 系列叠层片式超大电流磁珠 BCMS SERIES MULTILAYER CHIP POWER BEAD
宏业规格型号 PRODUCT TYPE	
客户型号规格 CUSTOMER'S PRODUCT TYPE	

研发	品质	业务	批准

深圳市宏业兴电子有限公司 SHENZHEN HONGYEX ELECTRONICS CO,.LTD.
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工厂地址：惠州市罗阳镇鸿达工业区五号宏业兴工业园
Factory address:Hongyexing Industrial Park, No.5, Hongda Industrial Zone,Luoyang Town,Huizhou City,Guangdong Province,China

备注 REMARK:		
客户回签 CUSTOMER APPROVAL		
采购 PURCHASE	工程 ENGINEER	品质 QUALITY

履历表 Resume

序号 NO.	修改日期 DATE	修改内容 CHANGE CONTENT	版本号 Version NO.
1	2019.11.08	初版 First edition	A1
2	2019.11.29	更新联系方式 Update contact	A2
3	2020.03.01	更新物料 Update material	A3
4	2020.05.28	更新规格 Update specification	A4
5	2020.07.28	更新参数单位 Update parameter units	A5
6	2024.09.19	更新规格，更新联系地址 Update specification,Update contact	A6
7	2025.09.19	更新公司地址和内容的排版 Update the company address and content layout	A7
8	2026.05.08	更新 BCMS 系列的参数 Update the parameters of the BCMS series	A8
9	2026.10.15	修正 403022、451616、453215、453223、853022 系列的载带信息 Correct the carrier tape information for the 403022, 451616, 453215, 453223, and 853022 series.	A9

1 用途 APPLICATIONS

广泛应用于通信、影音设备、计算机、遥控等领域。

Widely use in Communications, Video and audio equipment, Computer, Remote control, etc.

2 特点 FEATURES

高可靠的一体化结构；

Monolithic structure for high reliability;

尺寸小；

Compact size inductor possible;

磁屏蔽结构，不受干扰；

No cross coupling due to magnetic shield;

适用于各类表面贴装工艺；

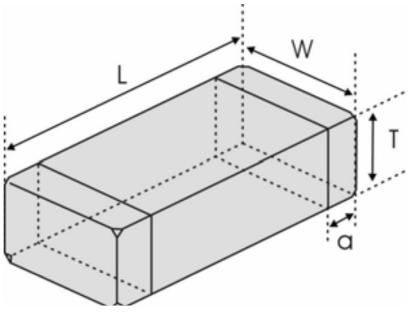
Perfect shape for mounting with no directionality;

3 产品品名组成 PRODUCT IDENTIFICATION

BCMS	201209	A	300	6A
①	②	③	④	⑤

①	Type：Chip Ferrite Bead
②	External Dimensions (L×W×T) (mm)：2.0×1.2×0.85
③	Material Code: A, B, K
④	Nominal Inductance：300，30Ω
⑤	Rated Current：6A

4 外形及尺寸 SHAPE AND DIMENSIONS



Unit: mm[inch]

Type	L	W	T	a
BCMS160808 [0603]	1.6±0.15 [.063±.006]	0.8±0.15 [.031±.006]	0.8±0.15 [.031±.006]	0.3±0.2 [.012±.008]
BCMS201209 [0805]	2.0(+0.3,-0.1) [.079(+.012,-.004)]	1.25±0.2 [.049±.008]	0.85±0.2 [.033±.008]	0.5±0.3 [.020±.012]
BCMS201212 [0805]	2.0(+0.3,-0.1) [.079(+.012,-.004)]	1.25±0.2 [.049±.008]	1.25±0.2 [.049±.008]	0.5±0.3 [.020±.012
BCMS321609 [1206]	3.2±0.2 [.126±.008]	1.6±0.2 [.063±.008]	0.85±0.2 [.033±.008]	0.5±0.3 [.020±.012]
BCMS321611 [1206]	3.2±0.2 [.126±.008]	1.6±0.2 [.063±.008]	1.1±0.2 [.043±.008]	0.5±0.3 [.020±.012]
BCMS322513 [1210]	3.2±0.2 [.126±.008]	2.5±0.2 [.098±.008]	1.3±0.3 [.051±.012]	0.5±0.3 [.020±.012]
BCMS403022	4.06±0.2 [.16±.008]	3.05±0.2 [.12±.008]	2.28±0.2 [.09±.008]	0.89±0.2 [.035±.008]
BCMS451616 [1806]	4.5±0.2 [.177±.008]	1.6±0.2 [.063±.008]	1.6±0.3 [.063±.003]	0.5±0.3 [.020±.012]
BCMS453215 [1812]	4.5±0.2 [.177±.008]	3.2±0.2 [.126±.008]	1.5±0.3 [.059±.012]	0.5±0.3 [.020±.012]
BCMS453223	4.5±0.25	3.2±0.25	2.3±0.25	0.8±0.2

[1812]	[.177±.01]	[.126±.01]	[.091±.01]	[.032±.008]
BCMS853022	8.5±0.2 [.335±.008]	3.05±0.2 [.12±.008]	2.28±0.2 [.09±.008]	0.89±0.2 [.035±.008]

5 特性参数 SPECIFICATIONS

详见附录 A。Please refer to Appendix A.

工作温度范围 Operating temperatrue range: -40℃~+125℃

储存温度范围 Storage temperature range: -10℃~+40℃

6 测试及可靠性 TESTING AND RELIABILITY

6.1 测试环境条件 Test Conditions

一般按照以下环境条件测试（有特殊要求的除外），：

Unless otherwise specified, the standard atmospheric conditions for measurement/test as:

a. 温度 Ambient Temperature: 20±15℃

b. 湿度 Relative Humidity: 65±20%

c. 大气压 Air Pressure: 86 kPa to 106 kPa

如果对测试结果有疑义，可以按照以下条件复测：

If any doubt on the results, measurements/tests should be made within the following limits:

a. 温度 Ambient Temperature: 20±2℃

b. 湿度 Relative Humidity: 65±5%

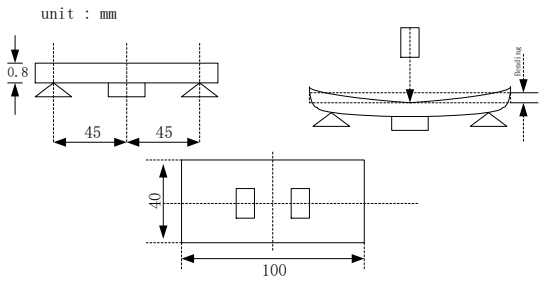
c. 大气压 Air Pressure: 86kPa to 106 kPa

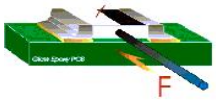
6.2 电性测试 Electrical Performance Testing

测试 Testing	测试方法与要求 Test Methods and Remarks
直流电阻 RDC	a. 标准值参考第 5 章节附录 A。Refer to Item 5 Appendix A. b. 测试仪器：高精度电阻表 HP4338B 或等效仪器。Test equipment (Analyzer): High Accuracy Milliohmmeter-HP4338B or equivalent.
阻抗值 Impedance (|Z|)	a. 标准值参考第 5 章节附录 A。Refer to Item 5 Appendix A. b. 测试仪器：高精度射频阻抗分析仪 Anglient E4991A+HP16192A 或等效仪器。 Test equipment: High Accuracy RF Impedance /Material Analyzer -Anglient E4991A+ HP16192A or equivalent. c. 测试信号 Test signal: -40dBm or 100mV. d. 测试频率参考第 5 章节。Test frequency refers to Item 5.
额定电流 Rated Current（Ir）	a. 标准值参考第 5 章节。Refer to Item 5. b. 测试仪器：HP6632B 直流电源，数字点温计或等效仪器。 Test equipment: HP6632B system DC power supply, digital surface thermometer or equivalent. c. 额定电流＜1A，温升ΔT≤20℃；额定电流≥1A，温升ΔT≤40℃。Rated Current ＜1A，ΔT≤20℃；Rated Current ≥1A，ΔT≤40℃ .

6.3 可靠性测试 Reliability Testing

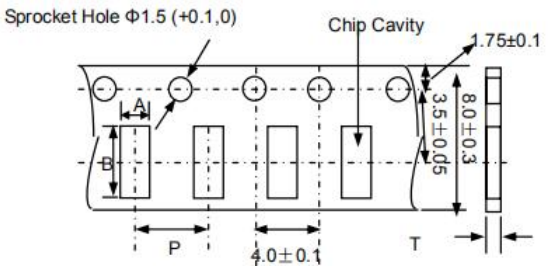
可焊性 SOLDER－ABILITY	至少 95%的焊接面完全被焊锡连续覆盖。95% min. coverage of all metabolised area. 焊锡温度 Solder temp. : 240±5℃ 浸入时间 Immersion time : 3±1 sec 焊锡 Solder : Sn-3Ag-0.5Cu
耐焊性	无可见损伤。电特性和机械特性满足产品规范或检验标准要求。No visible damage. Electrical characteristics and mechanical characteristics shall be satisfied. 焊锡温度 Solder Temp. : 265±3℃

RESISTANCE TO SOLDER HEAT	浸入时间 Immersion time : 6±1 sec 预热 Preheating : 100℃ to 150℃, 1 minute. 在室温下放置 24±2 小时后测试检查。Measurement to be made after keeping at room temp for 24±2 hrs. 焊锡 Solder : Sn-3Ag-0.5Cu
弯曲 Bend	试验后无破损现象，阻抗值应在±25%以内，直流电阻应符合标准/规范要求。Without deformation cases, Impedance shall be satisfied ± 25%, DC resistance shall be satisfied. 将产品焊接在试验板上，如图所示在试验板中间位置施加压力，使得试验板中心点向下弯曲 2mm，保持 10 秒。After soldering a chip to a test substrate,bend the substrate by 2mm hold for 10s and then return. Soldering shall be done in accordance with the recommended PC board pattern and reflow soldering. 
振动 Vibration	a.试验要求 Performance specification 1）外观 Appearance：无可见机械损伤 no mechanical damage 2）阻抗值变化应在±25%以内 Impedance shall be with ±25％of the initial value b.试验条件 Test condition 1）波形 Waveform:正弦波 Sine wave 2）频率 Frequency:10~55~10 Hz 3）持续时间 Sweep time:1min 4）Amplitude:1.5mm(peak-peak) 5.Direction:X,Y,Z(3 axes) 6.Duration:2 hrs./axis,total 6 hrs.
温度冲击 Temperature shock	a.试验要求 Performance specification 1）外观 Appearance：无可见机械损伤 no mechanical damage 2）阻抗值变化应在±25%以内 Impedance shall be with ±25％of the initial value b.试验条件 Test condition 1）温度 Temperature ：-40℃,+125℃各保持 30 分钟。-40℃,+125℃ kept stabilized for 30 minutes each 2）周期 Cycle：5 次。5 cycles. 3）检查 Measurement：试验后至少在室温条件下放置 24 小时以上。After placing at room ambient temperature for 24 hours minimum.
湿热负载 HUMIDITY RESISTANCE	a.试验要求 Performance specification 1）外观 Appearance：无可见机械损伤 no mechanical damage 2）阻抗值变化应在±25%以内 Impedance shall be with ±25％of the initial value b.试验条件 Test condition 1）湿度 Humidity：90 to 95％RH 2）温度 Temperature：60±2℃ 3）加载电流 Applied current：额定直流电流 Rated current 4）试验时间 Testing tine：1000（+48,0）hours 5）检查 Measurement：试验后至少在室温条件下放置 24 小时以上。After placing at room ambient temperature for 24 hours minimum.
高温负载 HIGH TEMPERATURE RESISTANCE	a. 试验要求 Performance specification 1) 外观 Appearance：无可见机械损伤 no mechanical damage 2) 阻抗值变化应在±25%以内 Impedance shall be with ±25％of the initial value b. 试验条件 Test condition 1) 温度 Temperature： +125℃±2℃ 2) 加载电流 Applied current：额定直流电流 Rated current 3) 试验时间 Testing time：1000（+48,0）hours 4) 检查 Measurement：试验后至少在室温条件下放置 24 小时以上。After placing at room ambient temperature for 24 hours minimum.
	a.试验要求 Performance specification 1）外观 Appearance：无可见机械损伤 no mechanical damage.

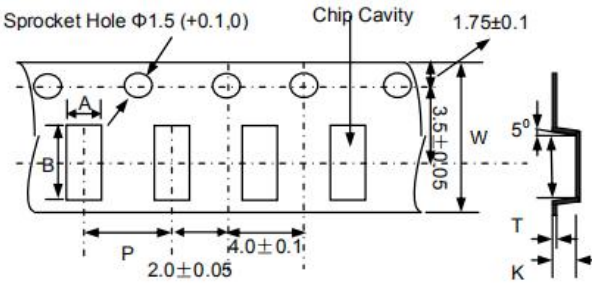
低温储存 LOW TEMPERATURE STORAGE LIFE	2）阻抗值变化应在±25%以内 Impedance shall be with ±25％of the initial value. b.试验条件 Test condition 1.温度 Temperature：-40℃±2℃ 2.试验时间 Testing time：1000（+48,0）hours 3.检查 Measurement：试验后至少在室温条件下放置 24 小时以上。After placing for 24 hours minimum at room ambient temperature.
端头强度 TERMINAL STRENGTH	无破损现象。Without deformation cases. 阻抗值变化应在±25%以内。Impedance shall be satisfied ± 25%. 直流电阻应满足标准要求。DC resistance shall be satisfied. 焊接在 PCB 上的产品应持续成熟 10N 推力共 10 秒，0603[0201]产品推力为 2N。Solder chip on PCB and applied 10N(1.02Kgf) for 10 sec.0603[0201] chip applied 2N. 
跌落 Drop	试验后产品应无失效现象。Products shall be no failure after test. 产品跌落在混凝土地面或钢板上。It shall be dropped on concrete or steel board. 试验方法：自由落下。Method : free fall. 高度 Height : 100cm. 产品跌落方向：3 个方向。Attitude from which the product is dropped : 3 direction. 总次数：每个方向 3 次（共 9 次）。The number of times : 3 times for each direction (Total 9 times).
盐雾 Salt mist	a.试验要求 Performance specification 1）外观 Appearance：无可见机械损伤 no mechanical damage. 2）阻抗值变化应在±25%以内 Impedance shall be with ±25％of the initial value. b.试验条件 Test condition 1）盐溶液溶度 Concentration of salt solution：（5±0.1）%. 2）PH：6.5-7.2 3）时间 Time：48±2h

7 包装 PACKAGING

7.1 载带尺寸 Tape Dimensions(Unit: mm)

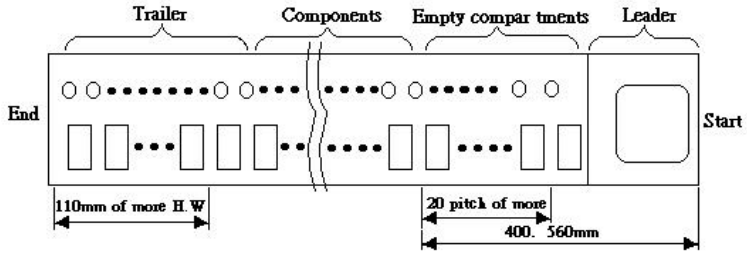


Paper Tape				
型号 Type	A	B	P	T max
1608[0603]	1.0±0.2	1.8±0.2	4.0±0.1	1.1
201209[0805]	1.5±0.2	2.3±0.2	4.0±0.1	1.1
321609[1206]	1.9±0.2	3.5±0.2	4.0±0.1	1.1

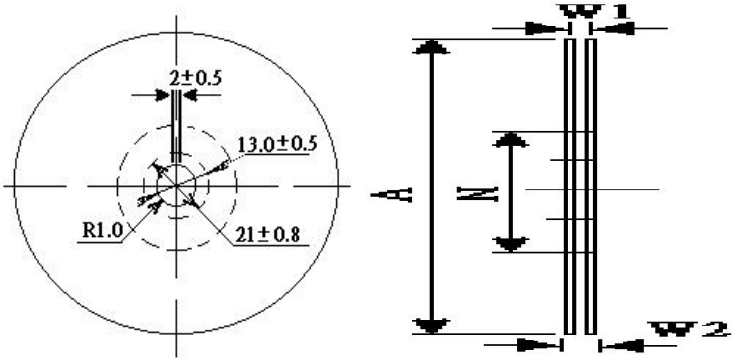


Embossed Tape						
型号 Type	A	B	W	P	K max	T max
201212[0812]	1.55±0.2	2.25±0.2	8.0±0.3	4.0±0.1	1.45	0.3
321611[1211]	1.88±0.2	3.5±0.2	8.0±0.3	4.0±0.1	1.27	0.3
3225[1210]	2.9±0.2	3.5±0.2	8.0±0.3	4.0±0.1	1.65	0.28
4516[1806]	1.93±0.2	4.95±0.2	12.0±0.3	4.0±0.1	2.03	0.35
403022	3.3±0.2	4.39±0.2	12.0±0.3	8.0±0.1	2.87	0.32
453215[1812]	3.66±0.2	4.95±0.2	12.0±0.3	8.0±0.1	1.95	0.33
453223[1812]	3.66±0.2	4.95±0.2	12.0±0.3	8.0±0.1	2.73	0.35
853022	3.66±0.2	8.92±0.2	16.0±0.3	8.0±0.1	2.77	0.38

7.2 载带 Tape



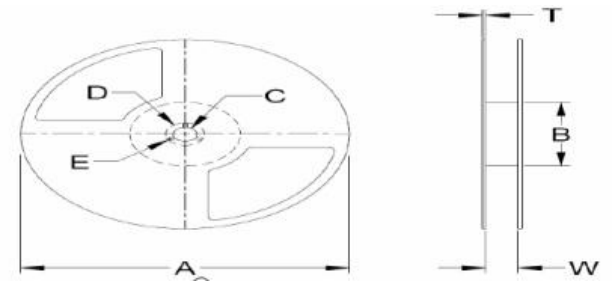
7.3 卷盘尺寸 Reel Dimensions



UNIT:mm

A	178 ±2.0
N	50 MIN
W1	10 ±1.5
W2	20 MAX

型号 Type	T(mm)	载带 Tape	数量 Quantity
1608[0603]	0.8±0.15	Paper Tape	4K
2012[0805]	0.85±0.2	Paper Tape	4K
	1.25±0.2	Embossed Tape	3K
3216[1206]	0.85±0.2	Paper Tape	4K
	1.1±0.2	Embossed Tape	3K
3225[1210]	1.3±0.3	Embossed Tape	2K
4516[1806]	1.6±0.3	Embossed Tape	2K
4532[1812]	1.5±0.3	Embossed Tape	1K

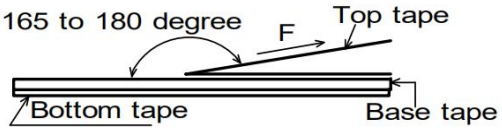


UNIT:mm

A	B	C	D
330 ±2	60 ±1	13 ±0.5	21 ±0.8
E	W	T	
2 ±0.5	16 ±1	2 ±0.5	

型号 Type	T(mm)	载带 Tape	数量 Quantity
403022	2.28±0.2	Embossed Tape	2.5K
4532[1812]	2.3±0.25	Embossed Tape	2.5K
853022	2.28±0.2	Embossed Tape	2.5K

7.4 剥离力 PEELING OFF FORCE



剥离速度 Speed of peeling off	300mm/s
剥离力 Peeling off force	0.1N to 1N(10g to 100g).

7.5 包装 Packaging

a. 卷盘和干燥剂一同放入尼龙或塑料袋中。Reel and a bag of desiccant shall be packed in Nylon or plastic bag.

b. 每个内盒中最多装 2 个上述袋子。Maximum of 2 bags shall be packaged in a inner box.

c. 每个外箱中最多装 8 个内盒。Maximum of 8 inner box shall be packaged in a outer box.

8 储存 Storage

8.1 不得暴露在高温高湿环境下储存，否则导致产品外电极和焊接性恶化变差。建议包装好的产品储存在低于 40℃、小于 70% RH 条件下。

The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Packages must be stored at 40℃ or less and 70％RH or less.

8.2 不得暴露在灰尘或腐蚀性气体（如氯化氢，亚硫酸气体或硫化氢等）环境下储存，否则会导致产品外电极和焊接性恶化变差。

The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust or harmful gas (hydrogen chloride, sulfurous acid gas or hydrogen sulfide).

8.3 如果暴露在阳光直射或加热环境下储存，会导致包装材料变形。

Packaging material may be deformed if packages are stored where they are exposed to heat or direct sunlight.

8.4 采用聚乙烯热封载带形式的最小包装，在使用之前不要拆开。如果拆开了，应尽快使用卷盘保护起来。

Minimum packages, such as polyvinyl heat-seal packages shall not be opened until just before they are used.If opened, use the reels as soon as possible.

8.5 在符合 8.1 和 8.2 要求的环境下储存，从产品发货日期开始 6 个月内，产品的焊接性能够满足 6.3 规定的要求。

Solderability specified in composite specification 6.3 shall be for 6 months from the date of delivery on condition that they are stored at the environment specified clause 8.1 & 8.2.

8.6 在产品使用之前，如果储存期超过 6 个月，则需要复检焊接性。

For those parts which passed more than 6 months shall be checked solderability before it is used.

9 焊接及注意事项

9.1 回流焊条件 Reflow soldering conditions

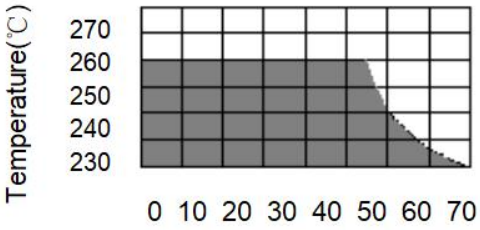
焊接之前产品应预热到 150℃。焊接后应冷却到 100℃。Pre-heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150℃ max.Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100℃ max.

如果预热不充分，会导致产品质量恶化。Unenough pre－heating may cause cracks on the ferrite, resulting in the deterioration of product quality.

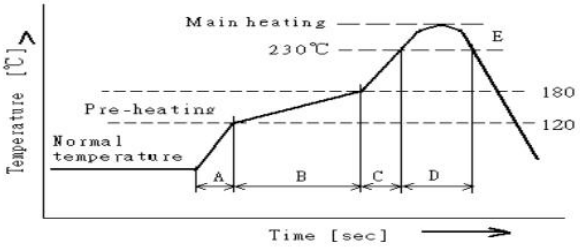
产品应当按照下述曲线焊接。Products should be soldered within the following allowable range indicated by the slanted line.

作业前，应对焊锡炉进行校准确认，保证能够符合焊接工艺条件。The excessive soldering conditions may

cause the corrosion of the electrode, When soldering is repeated, allowable time is the accumulated time.



Temperature Profile



A	Slope of temp. rise	※ 1 to 5	※ ℃/sec
B	Heat time	50 to 150	※ sec
	Heat temperature	120 to 180	※ ℃
C	Slope of temp. rise	1 to 5	※ ℃/sec
D	Time over 230℃	90~120	※ sec
E	Peak temperature	255~260	※ ℃
	Peak hold time	10 max.	※ sec
	※ No. of mounting	3	※ times

9.2 返工 Reworking with soldering iron

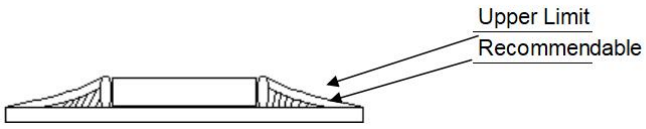
预热 Preheating	150℃, 1 minute
最高温度 Tip temperature	280℃ max
焊接时间 Soldering time	3seconds max.
电烙铁输出功率 Soldering iron output	30w max.
电烙铁焊头尺寸 End of soldering iron	ϕ 3mm max.

*返工仅限一次。Reworking should be limited to only one time.

注意 Note：为了避免焊接高温冲击导致产品本体开裂，电烙铁焊头焊锡时应避免直接与产品接触。Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the ferrite material due to the thermal shock.

9.3 焊料量 Solder Volume

焊料使用时，不得超过如下所示的上限要求。Solder shall be used not to be exceed the upper limits as shown below.



随着焊料的增加，产品承受的机械应力也随之增加。过量的焊料所产生的机械应力，会导致产品出现机械或电气特性失效。Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.

附录 A 电气特性表

Appendix A Electrical Characteristics

BCMS1608 Series

Part Number	Impedance	Max.DC resistance	Max.rated Current	Thichness
Unit	Ω@100MHz	mΩ	mA	mm[inch]
Symbol	|Z|	DCR	Ir	T
BCMS160808A100 4A	0~15	30	4000	0.8±0.15 [.031±.006]
BCMS160808A100 6A	0~15	10	6000	
BCMS160808A220 6A	22±25%	10	6000	
BCMS160808A220 8A	22±25%	8	8000	
BCMS160808A260 6A	26±25%	10	6000	
BCMS160808A300 4A	30±25%	30	4000	
BCMS160808A300 5A	30±25%	20	5000	
BCMS160808A300 6A	30±25%	10	6000	
BCMS160808A400 4A	40±25%	30	4000	
BCMS160808A700 4A	70±25%	30	4000	

BCMS2012 Series

Part Number	Impedance	Max.DC resistance	Max.rated Current	Thichness
Unit	Ω@100MHz	mΩ	mA	mm[inch]
Symbol	|Z|	DCR	Ir	T
BCMS201209A070 6A	0~15	10	6000	0.85±0.2 [.033±.008]
BCMS201209A100 6A	0~15	10	6000	
BCMS201209A110 6A	0~15	10	6000	
BCMS201209A150 6A	15±25%	10	6000	
BCMS201209A170 6A	17±25%	10	6000	
BCMS201209A190 6A	19±25%	10	6000	
BCMS201209A200 6A	20±25%	10	6000	
BCMS201209A220 6A	22±25%	10	6000	
BCMS201209A250 6A	25±25%	10	6000	
BCMS201209A300 4A	30±25%	30	4000	
BCMS201209A300 6A	30±25%	10	6000	
BCMS201209A390 6A	39±25%	10	6000	
BCMS201209A600 4A	60±25%	30	4000	
BCMS201209A600 6A	60±25%	20	6000	
BCMS201209A700 6A	70±25%	20	6000	
BCMS201209A800 4A	80±25%	40	4000	
BCMS201209A800 5A	80±25%	25	5000	

BCMS201209A800 6A	80±25%	20	6000	
BCMS201209A101 4A	100±25%	35	4000	
BCMS201209A101 5A	100±25%	25	5000	
BCMS201209A121 4A	120±25%	35	4000	
BCMS201209A121 5A	120±25%	25	5000	
BCMS201209A121 6A	120±25%	20	6000	
BCMS201209A181 4A	180±25%	35	4000	
BCMS201209A301 4A	300±25%	35	4000	

BCMS3216 Series

Part Number	Impedance	Max.DC resistance	Max.rated Current	Thichness
Unit	Ω@100MHz	mΩ	mA	mm[inch]
Symbol	|Z|	DCR	Ir	T
BCMS321609A000 4A	0~15	25	4000	
BCMS321609A000 6A	0~15	10	6000	
BCMS321609A050 6A	0~15	10	6000	
BCMS321609A100 6A	0~15	10	6000	
BCMS321609A110 6A	0~15	10	6000	
BCMS321609A120 6A	0~15	10	6000	
BCMS321609A150 6A	15±25%	15	6000	
BCMS321609A190 6A	19±25%	15	6000	
BCMS321609A260 6A	26±25%	15	6000	
BCMS321609A300 4A	30±25%	25	4000	
BCMS321609A300 6A	30±25%	15	6000	
BCMS321609A500 4A	50±25%	25	4000	0.85±0.2 [.033±.008]
BCMS321609A500 6A	50±25%	15	6000	
BCMS321609A600 4A	60±25%	25	4000	
BCMS321609A600 6A	60±25%	15	6000	
BCMS321609A800 5A	80±25%	25	5000	
BCMS321609A800 6A	80±25%	20	6000	
BCMS321609A101 4A	100±25%	35	4000	
BCMS321609A101 5A	100±25%	25	5000	
BCMS321609A101 6A	100±25%	20	6000	
BCMS321609A121 4A	120±25%	35	4000	
BCMS321609A121 5A	120±25%	25	5000	
BCMS321609A121 6A	120±25%	20	6000	
BCMS321609A151 5A	150±25%	30	5000	
BCMS321611A190 4A	19±25%	25	4000	1.1±0.2 [.043±.008]
BCMS321611A300 6A	30±25%	15	6000	

BCMS321611A300 8A	30±25%	10	8000	
BCMS321611A330 6A	33±25%	15	6000	
BCMS321611A500 4A	50±25%	25	4000	
BCMS321611A500 6A	50±25%	15	6000	
BCMS321611A500 12A	50±25%	2.5	12000	
BCMS321611A520 6A	52±25%	15	6000	
BCMS321611A600 5A	60±25%	20	5000	
BCMS321611A600 6A	60±25%	15	6000	
BCMS321611A800 4A	80±25%	25	4000	
BCMS321611A800 6A	80±25%	20	6000	
BCMS321611A101 6A	100±25%	20	6000	
BCMS321611A121 5A	120±25%	25	5000	
BCMS321611A121 6A	120±25%	20	6000	

BCMS3225 Series

Part Number	Impedance	Max.DC resistance	Max.rated Current	Thichness
Unit	Ω@100MHz	mΩ	mA	mm[inch]
Symbol	|Z|	DCR	Ir	T
BCMS322513A000 6A	0~15	10	6000	
BCMS322513A100 5A	0~15	20	5000	
BCMS322513A110 6A	0~15	10	6000	
BCMS322513A150 6A	15±25%	10	6000	
BCMS322513A190 5A	19±25%	30	5000	
BCMS322513A260 5A	26±25%	30	5000	
BCMS322513A300 5A	30±25%	30	5000	
BCMS322513A300 6A	30±25%	20	6000	
BCMS322513A300 10A	30±25%	1.6	10000	
BCMS322513A310 6A	31±25%	20	6000	
BCMS322513A450 6A	45±25%	20	6000	1.3±0.3 [.051±.012]
BCMS322513A500 6A	50±25%	20	6000	
BCMS322513A520 6A	52±25%	20	6000	
BCMS322513A600 5A	60±25%	30	5000	
BCMS322513A600 6A	60±25%	20	6000	
BCMS322513A700 5A	70±25%	30	5000	
BCMS322513A800 6A	80±25%	20	6000	
BCMS322513A121 5A	120±25%	30	5000	
BCMS322513A151 5A	150±25%	30	5000	
BCMS322513A181 5A	180±25%	30	5000	
BCMS322513A221 4A	220±25%	60	4000	

BCMS322513A221 5A	220±25%	30	5000	
BCMS322513A301 4A	300±25%	60	4000	
BCMS322513A501 4A	500±25%	100	4000	

BCMS4516 Series

Part Number	Impedance	Max.DC resistance	Max.rated Current	Thichness
Unit	Ω@100MHz	mΩ	mA	mm[inch]
Symbol	|Z|	DCR	Ir	T
BCMS451616A560 6A	56±25%	10	6000	1.6±0.3 [.063±.012]
BCMS451616A600 6A	60±25%	10	6000	
BCMS451616A720 6A	72±25%	10	6000	
BCMS451616A750 6A	75±25%	10	6000	

BCMS4030 Series

Part Number	Impedance	Max.DC resistance	Max.rated Current	Thichness
Unit	Ω@100MHz	mΩ	mA	mm[inch]
Symbol	|Z|	DCR	Ir	T
BCMS403022I560 6A	56±25%	10	6000	2.28±0.2 [0.09±0.008]
BCMS403022I560 10A	56±25%	4	10000	

BCMS4532 Series

Part Number	Impedance	Max.DC resistance	Max.rated Current	Thichness
Unit	Ω@100MHz	mΩ	mA	mm[inch]
Symbol	|Z|	DCR	Ir	T
BCMS453223I101 8A	100±25%	7	8000	2.3±0.25 [0.091±0.01]
BCMS453215A000 6A	0~15	10	6000	1.5±0.3 [.059±.012]
BCMS453215A190 6A	19±25%	10	6000	
BCMS453215A300 6A	30±25%	10	6000	
BCMS453215A310 6A	31±25%	10	6000	
BCMS453215A500 6A	50±25%	10	6000	
BCMS453215A600 6A	60±25%	10	6000	
BCMS453215A600 9A	60±25%	10	9000	
BCMS453215A700 6A	70±25%	15	6000	
BCMS453215A800 6A	80±25%	15	6000	
BCMS453215A800 9A	80±25%	10	9000	
BCMS453215A101 6A	100±25%	20	6000	
BCMS453215A101 8A	100±25%	10	8000	
BCMS453215A121 6A	120±25%	20	6000	

BCMS453215A121 9A	120±25%	10	9000	
BCMS453215A151 5A	150±25%	20	5000	
BCMS453215A151 6A	150±25%	20	6000	
BCMS453215A181 6A	180±25%	20	6000	
BCMS453215A221 6A	220±25%	20	6000	
BCMS453215K681 4A	680±25%	30	4000	
BCMS453215A881 4A	880±25%	40	4000	

BCMS5650 Series

Part Number	Impedance	Max.DC resistance	Max.rated Current	Thichness
Unit	Ω@100MHz	mΩ	mA	mm[inch]
Symbol	|Z|	DCR	Ir	T
BCMS565015I171 4A	170±25%	30	4000	1.52±0.25 [0.06±0.01]
BCMS565018I101 6A	100±25%	6	6000	1.8±0.25 [0.071±0.01]
BCMS565018I151 5A	150±25%	15	5000	
BCMS565018I181 5A	180±25%	20	5000	
BCMS565018I251 4A	250±25%	15	4000	
BCMS565032I271 4A	270±25%	35	4000	3.2±0.25 [0.126±0.01]
BCMS565032I401 4.5A	400±25%	30	4500	
BCHS565036I801 8A	800±25%	10	8000	3.61±0.25 [0.142±0.01]

BCMS8530 Series

Part Number	Impedance	Max.DC resistance	Max.rated Current	Thichness
Unit	Ω@100MHz	mΩ	mA	mm[inch]
Symbol	|Z|	DCR	Ir	T
BCMS853022I101 10A	100±25%	4	10000	2.28±0.2 [0.09±0.008]